

PATENT ABSTRACTS OF JAPAN

(11) Publication number : 64-054749
 (43) Date of publication of application : 02.03.1989

(51) Int.CI.

H01L 23/28
 H01L 21/60
 H01L 23/50

(21) Application number : 62-211993
 (22) Date of filing : 26.08.1987

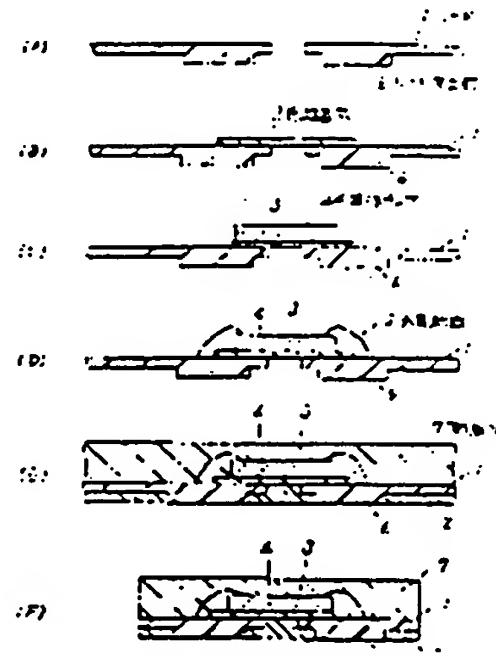
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(54) SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

(57) Abstract:

PURPOSE: To obtain a highly accurate and highly reliable semiconductor device by placing a semiconductor chip through an insulating substrate on one group of highly accurate metal leads, connecting the leads to fine metal wirings, and transfer molding them.

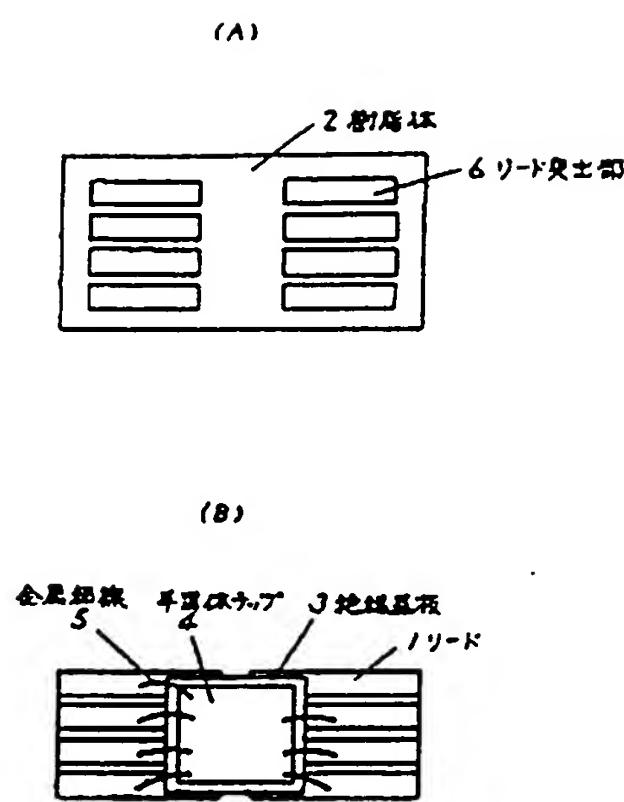
CONSTITUTION: A thin resin plate 3 is attached to leads 1 having protrusions 6, and electrodes on a semiconductor chip 4 are connected to the leads 1 by fine metal wirings 5. Then, the leads except the protrusions 6 are sealed with resins 2, 7, shape and size are determined and cut. According to this structure, a small-sized and thin semiconductor device having high dimensional accuracy and reliability is obtained without complicated structure like a both-side substrate only by employing metal leads of special shape at part, and is preferably adapted for an IC.



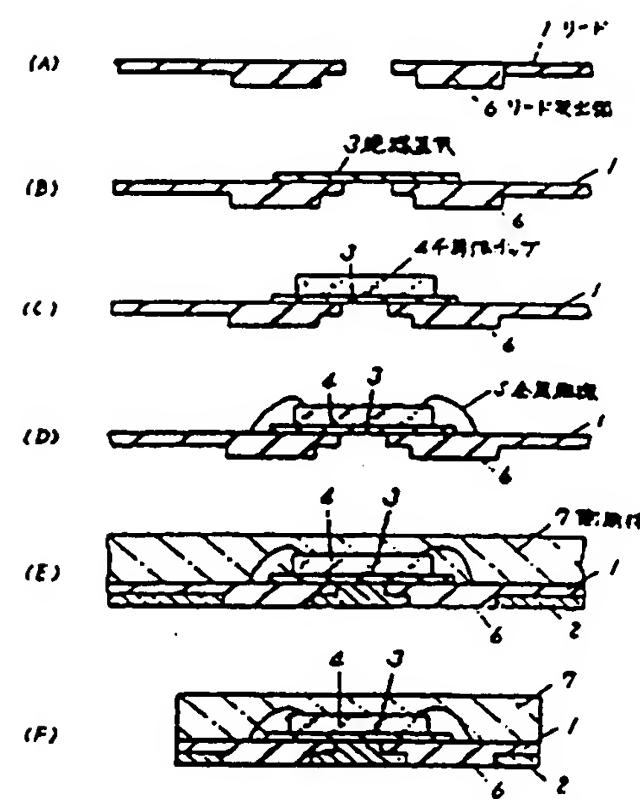
LEGAL STATUS

- [Date of request for examination]
- [Date of sending the examiner's decision of rejection]
- [Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]
- [Date of final disposal for application]
- [Patent number]
- [Date of registration]
- [Number of appeal against examiner's decision of rejection]
- [Date of requesting appeal against examiner's decision of rejection]
- [Date of extinction of right]

第2図



第3図



第4図

